

CMPA0530002S 2 W, 0.5 - 3.0 GHz, 28 V, Gan MMIC

Description

The CMPA0530002S is a packaged gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC). The MMIC power amplifier is matched to 50-ohms on the input. The CMPA0530002S operates on a 28 volt rail while housed in a 3mm x 4mm; surface mount; dual-flat-no-lead (DFN) package. Under reduced power; the transistor can operate below 28V to as low as 20V V_{DD} ; maintaining high gain and efficiency.



Package Type: 3x4 DFN PN: CMPA0530002S

Typical Performance Over $0.5 - 3.0 \text{ GHz} (T_c = 25^{\circ}\text{C}), 28 \text{ V}$

Parameter	0.5 GHz	1.0 GHz	1.5 GHz	2.0 GHz	2.5 GHz	3.0 GHz	Units
Small Signal Gain	18.10	17.90	18.30	17.90	17.90	17.52	dB
Output Power ¹	2.85	2.80	2.99	2.99	2.84	2.90	W
Power Gain ¹	13.05	12.97	13.26	13.25	13.04	13.12	dB
Power Added Efficiency ¹	56.0	48.7	56.2	51.2	46.0	49.1	%

¹Note: P_{IN} = 21.5 dBm, CW

Features for 28 V in CMPA0530002S-AMP

- 18 dB Small Signal Gain
- 2.9 W Typical P_{SAT}
- Operation up to 28 V
- High Breakdown Voltage
- High Temperature Operation
- Size 0.118 x 0.157 x 0.033 inches

Applications

- Civil and Military Communications
- Broadband Amplifiers
- Electronic Warfare
- Industrial, Scientific & Medical
- Radar



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Large Signal Models Available for ADS and MWO



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Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V _{DSS}	84	N	25%
Gate-to-Source Voltage	V _{GS}	-10, +2	v	25°U
Storage Temperature	T _{stg}	-65, +150	°C	
Operating Junction Temperature	۲J	225	Ĵ	
Maximum Forward Gate Current	I _{GMAX}	0.8	mA	25%
Maximum Drain Current ¹	I _{DMAX}	0.33	А	25°C
Soldering Temperature ²	Ts	245	°C	
Thermal Resistance, Junction to Case⁵	$R_{\theta JC}$	24.0	°C/W	85°C

Notes:

 $^{\scriptscriptstyle 1}$ Current limit for long term, reliable operation

² Refer to the Application Note on soldering

³ Simulated at $P_{DISS} = 2.2 \text{ W}$

⁴ T_C = Case temperature for the device. It refers to the temperature at the ground tab underneath the package. The PCB will add additional thermal resistance ⁵ The R_{TH} for the application circuit, CMPA0530002S-AMP1, with 15 (Ø13 mil) via holes designed on a 20 mil thick Rogers 4350B PCB, is 24°C/W.

The total R_{TH} from the heat sink to the junction is 24°C/W + 6.5°C/W = 30.5°C/W

Electrical Characteristics ($T_c = 25^{\circ}C$), 28 V Typical

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
DC Characteristics ¹							
Gate Threshold Voltage	$V_{GS(th)}$	-3.6	-3.1	-2.4	V	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 0.8 \text{ mA}$	
Gate Quiescent Voltage	$V_{GS(Q)}$	—	-2.4	—	mA	$V_{DS} = 28 \text{ V}, I_{D} = 90 \text{ mA}$	
Saturated Drain Current ²	I _{DS}	0.58	0.8	_	А	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$	
Drain-Source Breakdown Voltage	$V_{\text{BR}(\text{DSS})}$	84	_	-	V	$V_{GS} = -8 \text{ V}, I_{D} = 0.8 \text{ mA}$	
RF Characteristics ^{3,4} ($T_c = 25^{\circ}C$, $F_0 = 3.0$ GHz unless otherwise noted)							
Small Signal Gain	S ₂₁	—	16.4	_			
Input Return Loss	S ₁₁	—	-19.3	_	dB		
Output Return Loss	S ₂₂	_	-14.7	-		$V_{DS} = 28 \text{ V}, I_{DQ} = 90 \text{ mA}$	
Output Power	P _{out}	_	33.5	-	dBm		
Drain Efficiency	η	_	52	-	%		
Output Mismatch Stress	VSWR	_	_	10:1	Ψ	No damage at all phase angles, $V_{DD} = 28 \text{ V}$, $I_{DQ} = 90 \text{ mA}$, $P_{IN} = 23 \text{ dBm}$	

Notes:

¹ Measured on wafer prior to packaging.

² Scaled from PCM data

³ Measured in CMPA0530002S high volume test fixture at 3.0 GHz and may not show the full capability of the device due to source inductance and thermal performance.

 4 P_{IN} = 23 dBm, CW

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Electrical Characteristics When Tested in CMPA0530002S-AMP1 at 0.5 - 3.0 GHz, CW

Characteristics	Symbol	Тур.	Max.	Units	Conditions	
RF Characteristics ¹ ($T_c = 25^{\circ}C$, $F_0 = 0.5 - 3.0$ GHz unless otherwise noted)						
Gain ²	G	13.2	_	dB		
Output Power ²	P _{out}	34.6	-	dBm	$V_{DD} = 28 \text{ V}, I_{DQ} = 90 \text{ mA}, P_{IN} = 21.5 \text{ dBm}$	
Power Added Efficiency ²	η	51	-	%		
Output Mismatch Stress ²	VSWR	_	10:1	Ψ	No damage at all phase angles, $V_{DS} = 28 \text{ V}$, $I_{DQ} = 90 \text{ mA}$	

Notes:

¹ Measured in CMPA0530002S-AMP1 Application Circuit

 2 CW



Test conditions unless otherwise noted: V_{DD} = 28 V, I_{DO} = 90 mA, CW, P_{IN} = 21.5 dBm, Frequency = 2 GHz, T_{BASE} = +25°C



Figure 1. Output Power vs Frequency as a Function of Input Power



Figure 3. Drain Current vs Frequency as a Function of Input Power



Figure 5. Power Added Efficiency vs Frequency as a **Function of Temperature**



Figure 2. Power Added Efficiency vs Frequency as a Function of Input Power



Figure 4. Output Power vs Frequency as a Function of Temperature





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Figure 7. Output Power vs Frequency as a Function of Drain Voltage



Figure 9. Drain Current vs Frequency as a Function of Drain Voltage



Figure 11. Power Added Efficiency vs Frequency as a Function of IDO



Figure 8. Power Added Efficiency vs Frequency as a Function of Drain Voltage



Figure 10. Output Power vs Frequency as a Function of I_{DO}



Figure 12. Drain Current vs Frequency as a Function of I_{DO}

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Figure 13. Output Power vs Input Power as a Function of Frequency



Figure 15. Large Signal Gain vs Input Power as a Function of Frequency







Figure 14. Power Added Efficiency vs Input Power as a Function of Frequency



Figure 16. Drain Current vs Input Power as a Function of Frequency





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Figure 19. Power Added Efficiency vs Input Power as a Function of Temperature



Figure 21. Drain Current vs Input Power as a Function of Temperature



Figure 23. Output Power vs Input Power as a Function of I_{DQ}



Figure 20. Large Signal Gain vs Input Power as a Function of Temperature



Figure 22. Gate Current vs Input Power as a Function of Temperature







Test conditions unless otherwise noted: V_{DD} = 28 V, I_{DQ} = 90 mA, CW, P_{IN} = 21.5 dBm, Frequency = 2 GHz, T_{BASE} = +25°C



Figure 25. Large Signal Gain vs Input Power as a Function of I_{DO}



Figure 27. Gate Current vs Input Power as a Function of I_{DQ}



Figure 26. Drain Current vs Input Power as a Function of I_{DQ}



Test conditions unless otherwise noted: V_{DD} = 28 V, I_{DQ} = 90 mA, CW, P_{IN} = 21.5 dBm, Frequency = 2 GHz, T_{BASE} = +25°C



Figure 28. 2nd Harmonic vs Frequency as a Function of Temperature



Figure 30. 2nd Harmonic vs Output Power as a Function of Frequency



Figure 32. 2nd Harmonic vs Output Power as a Function of I_{DO}



Figure 29. 3rd Harmonic vs Frequency as a Function of Temperature



Figure 31. 3rd Harmonic vs Output Power as a Function of Frequency



Figure 33. 3rd Harmonic vs Output Power as a Function of I_{DO}



Test conditions unless otherwise noted: V_{DD} = 28 V, I_{DQ} = 90 mA, CW, P_{IN} = 21.5 dBm, Frequency = 2 GHz, T_{BASE} = +25°C



Figure 34. Input RL vs Frequency as a Function of Temperature



Figure 36. Gain vs Frequency as a Function of Temperature



Figure 38. Output RL vs Frequency as a Function of Temperature



Figure 35. Input RL vs Frequency as a Function of Temperature



Figure 37. Gain vs Frequency as a Function of Temperature



Figure 39. Output RL vs Frequency as a Function of Temperature



Test conditions unless otherwise noted: V_{DD} = 28 V, I_{DQ} = 90 mA, CW, P_{IN} = 21.5 dBm, Frequency = 2 GHz, T_{BASE} = +25°C



Figure 40. Input RL vs Frequency as a Function of Drain Voltage



Figure 42. Gain vs Frequency as a Function of Drain Voltage



Figure 44. Output RL vs Frequency as a Function of Drain Voltage



Figure 41. Input RL vs Frequency as a Function of Drain Voltage



Figure 43. Gain vs Frequency as a Function of Drain Voltage



Figure 45. Output RL vs Frequency as a Function of Drain Voltage



Test conditions unless otherwise noted: V_{DD} = 28 V, I_{DQ} = 90 mA, CW, P_{IN} = 21.5 dBm, Frequency = 2 GHz, T_{BASE} = +25°C



Figure 46. Input RL vs Frequency as a Function of I_{DQ}



Figure 48. Gain vs Frequency as a Function of IDQ



Figure 50. Output RL vs Frequency as a Function of I_{DQ}



Figure 47. Input RL vs Frequency as a Function of I_{DQ}



Figure 49. Gain vs Frequency as a Function of I_{DQ}



Figure 51. Output RL vs Frequency as a Function of I_{DQ}



CMPA0530002S-AMP1 Application Circuit Bill of Materials

Designator	Description	Qty
C1	CAP, 15pF, 5%, 0603, ATC600S	1
C2	CAP, 3.6pF, 5%, 0603, ATC600S	1
C4	CAP, 56pF, 5%, 0603, ATC600S	1
C8, C9	CAP, 100pF, 5%, 0603, ATC600S	2
C7, C10	CAP, 470pF, 5%, 100V, 0603, X7R, AVX	2
C6, C11	CAP, 1.0μF, 100V, 10%, X7R, 1210, muRata	2
C12	CAP, 33µF, 20%, G CASE, Panasonic	1
C13	CAP, 10µF, 16V, TANTALUM, 2312, AVX	1
L1	INDUCTOR, CHIP, 3.3nH, 0603 SMT, Coilcraft	1
L2	INDUCTOR, CHIP, 22nH, 0603 SMT, Coilcraft	1
L3	INDUCTOR, CHIP, 1.8nH,0603 SMT, Coilcraft	1
L4	INDUCTOR, CHIP, 33nH, 0603 SMT, Coilcraft	1
L5	INDUCTOR, CHIP, 1.6nH, 0603 SMT, Coilcraft	1
Q1	MMIC, GaN HEMT, DFN3x4, CMPA0530002S	1
	PCB, RO4350B, 0.020 THK, CMPA0530002S	1
	BASEPLATE, AL, 2.60 X 1.7 X 0.25	1
	2-56 SOC HD SCREW 1/4 SS	4
	#2 SPLIT LOCKWASHER SS	4
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
J3	HEADER RT>PLZ .1CEN LK 5POS	1
W1	Wire, Black, 22 AWG, ~ 1"	1

CMPA0530002S-AMP1 Application Circuit





CMPA0530002S-AMP1 Application Circuit Schematic



CMPA0530002S-AMP1 Application Circuit Outline



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CMPA0530002S Power Dissipation De-rating Curve



Note 1. Area exceeds Maximum Case Temperature (See Page 2)

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	НВМ	1A	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	C2B	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

Moisture Sensitivity Level (MSL) Classification

Parameter	Symbol	Class	Test Methodology
Moisture Sensitivity Level	MSL	3 (168 hours)	IPC/JEDEC J-STD-20



Source and Load Impedances



Frequency (GHz)	Z Source	Z Load
0.5	49.81 - j4.94	120.85 + j24.29
1.0	50.23 - j0.76	65.28 + j15.87
1.5	50.75 + j1.20	70.37 + j20.78
2.0	51.36 + j2.49	62.60 + j23.33
2.5	52.58 + j3.98	51.31 + j44.84
3.0	51.68 + j2.92	60.64 + j75.97

Notes:

 1 V_{DD} = 28V, I_{DQ} = 90mA

² Impedances are extracted from source and load pull data derived from the transistor



Product Dimensions CMPA0530002S (Package 3 x 4 DFN)

S Y	COMMON DIMENSIONS					
۱M,				No_		
Ľ	MIN.	NOM.	MAX.	ΓE		
A	0.80	0.90	1.0			
A1	0.00	0.02	0.05			
A3	(0.203 REF				
θ	0		12	2		
D	4.00 BSC					
E	3.00 BSC					
е	0.50 BSC					
Ν	12					
ND		6				
L	0.35	0.40	0.45			
b	0.18	0.25	0.30			
D2	3.20	3.30	3.40			
E2	1.60	1.7	1.80			
К	0.20					



Pin	Input/Output	
1	NC	
2	NC	fin iz
3	RF IN	
4	GND	
5	NC	
6	V _G	
7	NC	
8	NC	
9	GND	
10	RF OUT & V _{DD}	PIN 7
11	NC	
12	NC	

Note: Leadframe finish for 3x4 DFN package is Nickel/Palladium/Gold. Gold is the outer layer

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Part Number System



Table 1.

Parameter	Value	Units
Upper Frequency ¹	3.0	GHz
Power Output	2	W
Package	Surface Mount	_

Note:

¹ Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Table 2.

Character Code	Code Value
А	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
К	9
Examples	1A = 10.0 GHz 2H = 27.0 GHz



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CMPA0530002S	GaN HEMT	Each	2222255
CMPA0530002S-AMP1	Test board with GaN MMIC installed	Each	



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